

Multi-layer Chip Diplexer



ADID-R-0004

Request Samples 

Check Inventory 

1.0 x 0.5 x 0.4 mm

RoHS Compliant

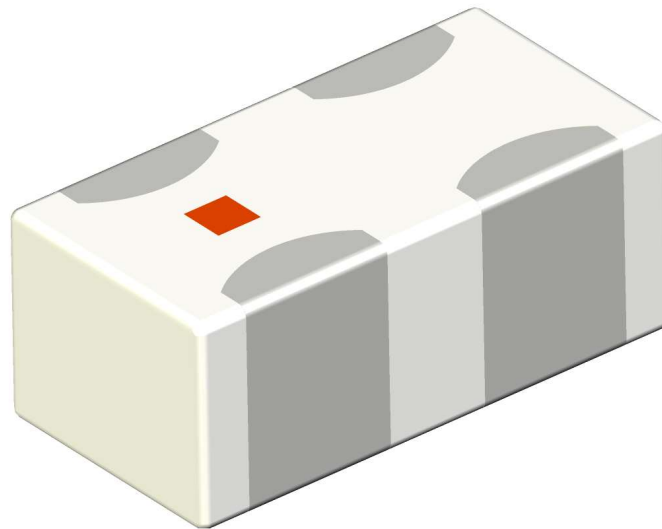
Features

- LTCC diplexer supporting 2400~2500 / 5150~7125 MHz
- Small Form Factor 1.0 x 0.5 x 0.4 mm
- Low Insertion Loss 0.5 dB
- VSWR as low as 1.2
- RoHS Compliant

Applications

- Wi-Fi 6/6E Standards
- Wi-Fi Speakers and Sound Bars
- Video Streaming and Network Cameras
- VR Head Mount Displays
- Car Infotainment Systems
- Broadband Gateways

Product Image



Multi-layer Chip Diplexer



ADID-R-0004

Request Samples

Check Inventory

1.0 x 0.5 x 0.4 mm

RoHS Compliant

Electrical Specifications

Parameters	Specification		Units	Notes
Center Frequency	2400-2500	5150-7125	MHz	
Insertion Loss (Max)	0.50	0.90	dB	@25°C
Insertion Loss (Max)	0.65	1.10		@-40~85°C
Absolute Attenuation	15.0 dB min. @4800~6000 MHz 15.0 dB min. @5150-7125 MHz 20.0 dB min. @7200-7500 MHz	24.0 dB min. @ 500~2400 MHz 26.0 dB min. @ 2400~2500 MHz 19.0 dB min. @ 2500~2690 MHz 9.0 dB min. @ 10300~11900 MHz 13.5 dB min. @ 11900~12490 MHz 11.5 dB min. @ 12490~14250 MHz 8.0 dB min. @ 15510~21375 MHz	dB	
Isolation (Min)	24	16.5	dB	
Return Loss (Min)	10		dB	@25°C
Power Capacity	2.0		W	-

Mechanical Specifications

Parameters	Specifications
Filter Dimension	1.0 x 0.5 x 0.4 mm
Mounting Type	SMD Mount

Environmental Specifications

Parameters	Specifications
Operating Temperature	-40°C ~ +85°C
Storage Temperature	-10°C ~ +45°C
Humidity	70% R.H.
RoHS Compliant	Yes

Multi-layer Chip Diplexer



ADID-R-0004

Request Samples

Check Inventory

1.0 x 0.5 x 0.4 mm

RoHS Compliant

Ordering Information

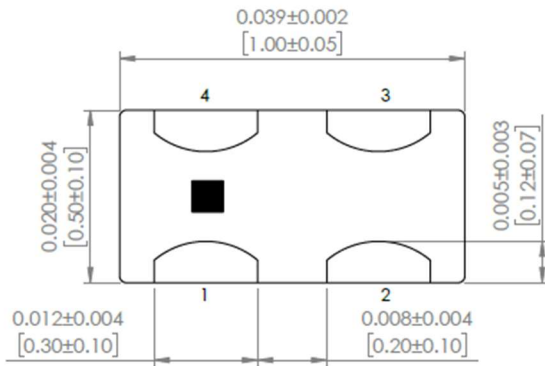
Part Identification

ADID-R-004

Packaging
Blank: Bulk
T: Tape & Reel

Package Dimensions & PCB Footprint

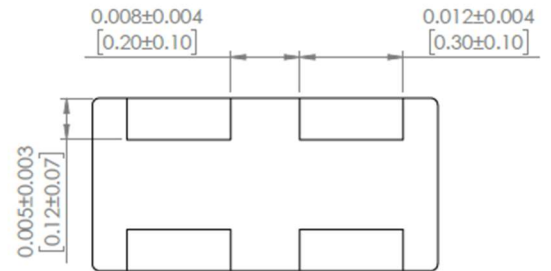
DIMENSIONS: INCHES [mm]



TOP VIEW



SIDE VIEW



BOTTOM VIEW



FRONT VIEW

Pin #	Function
1	Common Port
2	GND
3	High Freq. Port
4	Lower Freq. Port

Multi-layer Chip Diplexer



ADID-R-0004

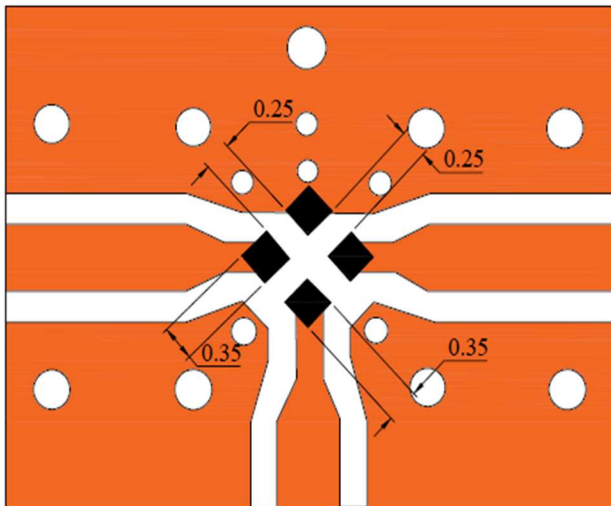
Request Samples

Check Inventory

1.0 x 0.5 x 0.4 mm

RoHS Compliant

Recommended Footprint (PCB Layout)



Solder Resist



Land



Through-hole (\varnothing 0.2 and 0.35)

Units: mm

Note: Line width to be designed to match 50Ω characteristic impedance, depending on PCB material and thickness.

The transmission line is Gound Coplanar Waveguide (GCPW)

Multi-layer Chip Diplexer



ADID-R-0004

Request Samples

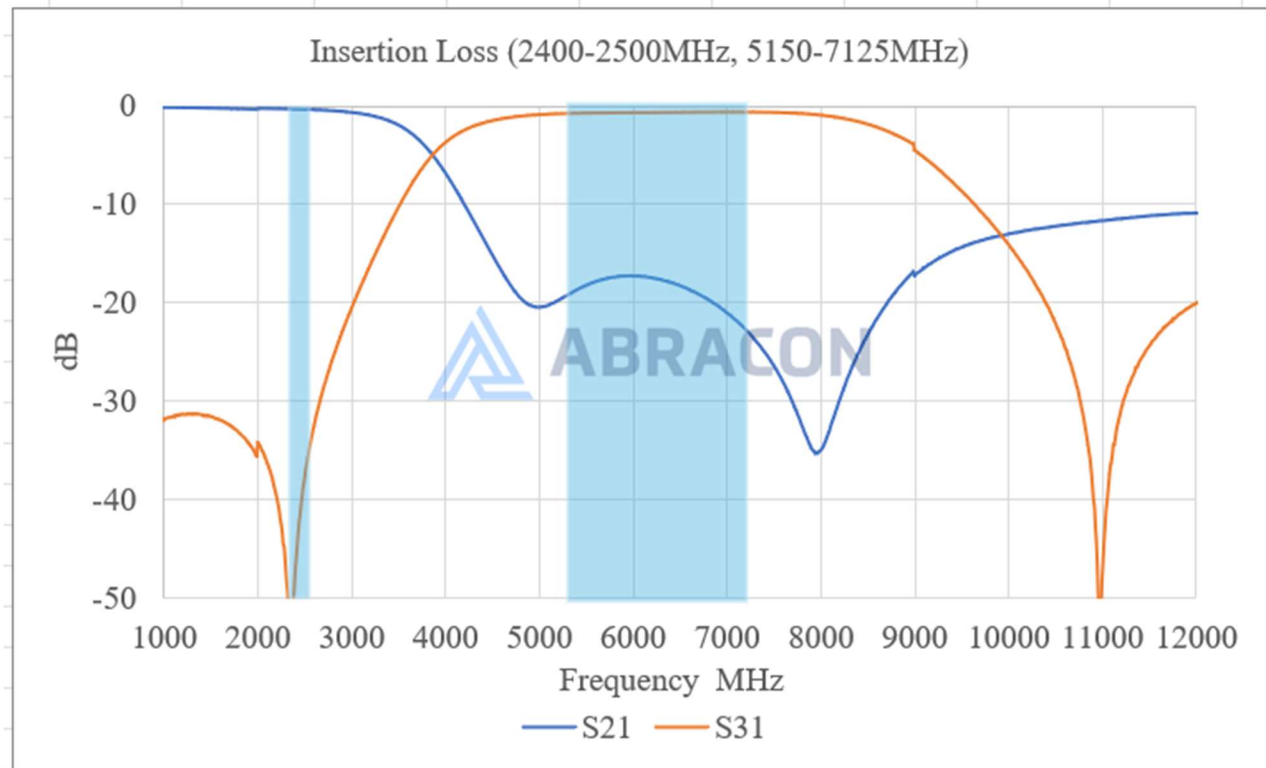
Check Inventory

1.0 x 0.5 x 0.4 mm

RoHS Compliant

Frequency Characteristics

Insertion Loss (S21 & S31) 2400-2500, 5150- 7125MHz



Multi-layer Chip Diplexer



ADID-R-0004

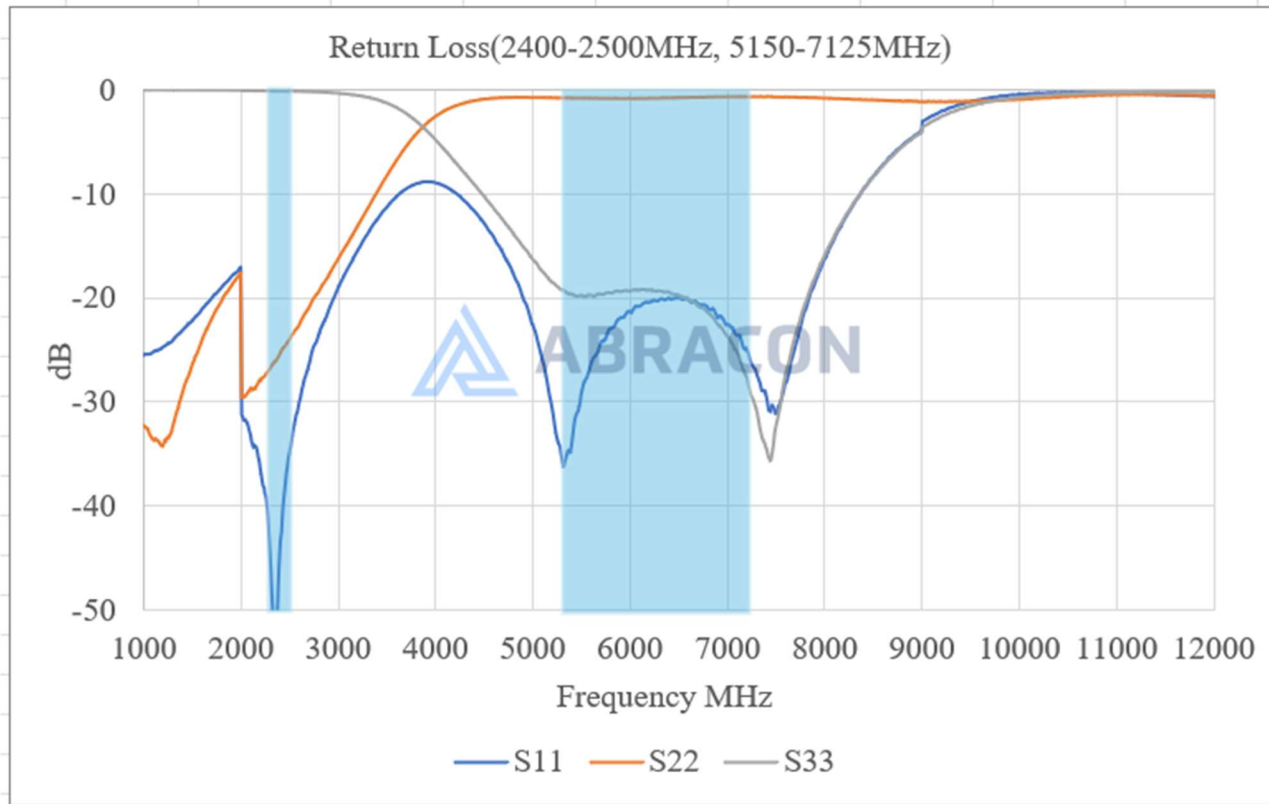
Request Samples

Check Inventory

1.0 x 0.5 x 0.4 mm

RoHS Compliant

Return Loss (S11 & S22 & S33)



Multi-layer Chip Diplexer



ADID-R-0004

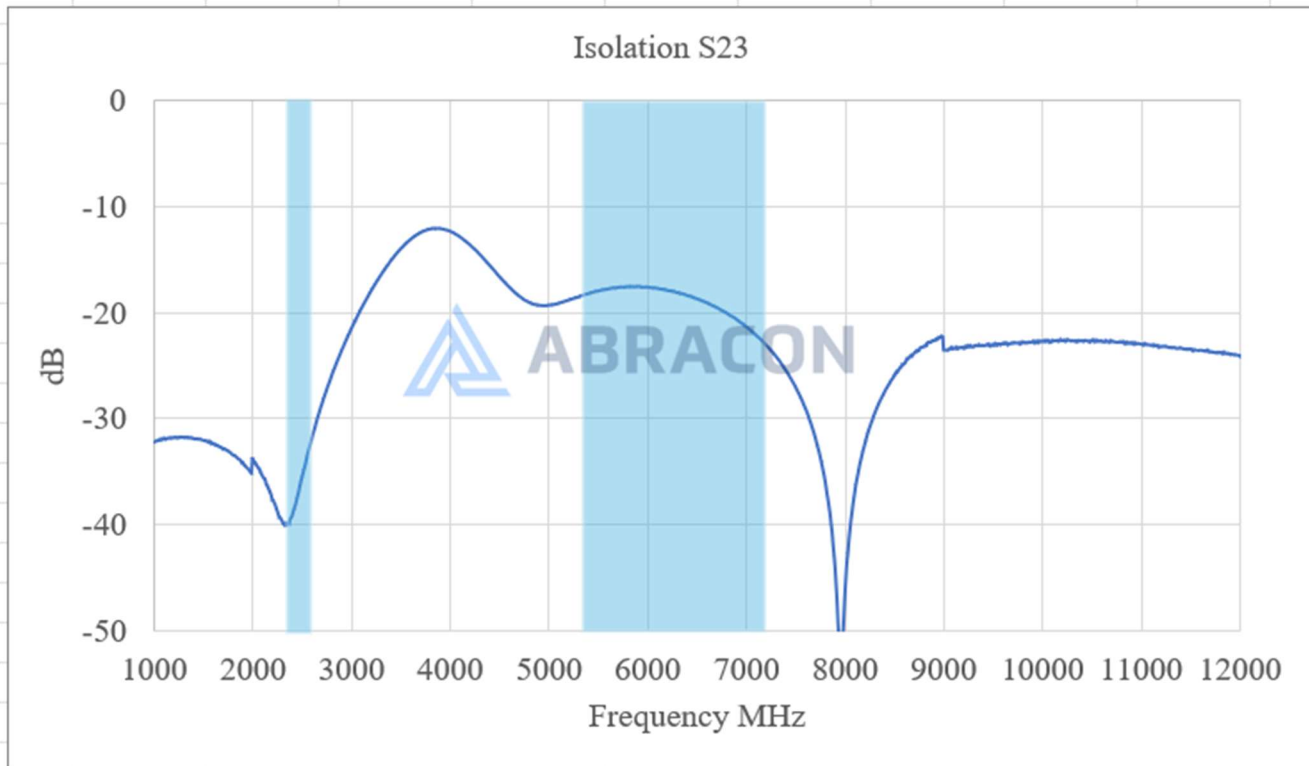
Request Samples

Check Inventory

1.0 x 0.5 x 0.4 mm

RoHS Compliant

Isolation (2400-2500, 5150- 7125MHz)



Multi-layer Chip Diplexer



ADID-R-0004

Request Samples

Check Inventory

1.0 x 0.5 x 0.4 mm

RoHS Compliant

Reflow Profile

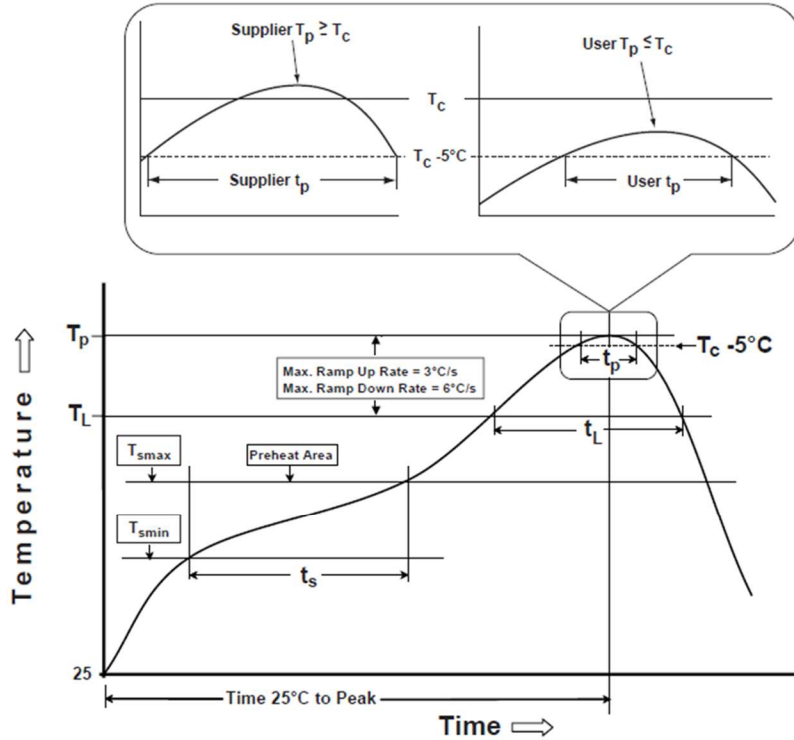


Table 1

SnPb Eutectic Process Classification Temperatures (T_c)		
Package Thickness	Volume mm^3 <350	Volume mm^3 \geq 350
<2.5 mm	235 °C	220 °C
\geq 2.5 mm	220 °C	220 °C

Table 2

Pb-Free Process Classification Temperatures (T_c)			
Package Thickness	Volume mm^3 <350	Volume mm^3 350-2000	Volume mm^3 >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm - 2.5 mm	260 °C	250 °C	245 °C
>2.5 mm	250 °C	245 °C	245 °C

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Preheat / soak		
Temperature minimum (T_{smin})	100°C	150°C
Temperature maximum (T_{smax})	150°C	200°C
Time (T_{smin} to T_{smax}) (t_s)	60 - 120 sec.	60 - 120 sec.
Average ramp-up rate (T_{smax} to T_p)	3°C/sec. max	3°C/sec. max
Liquidous temperature (T_L)	183°C	217°C
Time at liquidous (t_L)	60 - 150 sec.	60 - 150 sec.
Peak package body temperature (T_p)*	see Table 1	see Table 2
Time (t_p)** within 5°C of the specified classification temperature (T_c)	20 sec.	30 sec.
Ramp-down rate (T_p to T_{smax})	6°C/sec. max	6°C/sec. max
Time 25°C to peak temperature	6 min. max	8 min. max
Reflow cycles	2 max	2 max

*Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.

**Tolerance for time at peak profile temperature (t_p) is defined as supplier minimum and a user maximum.

Multi-layer Chip Diplexer



ADID-R-0004

Request Samples

Check Inventory

1.0 x 0.5 x 0.4 mm

RoHS Compliant

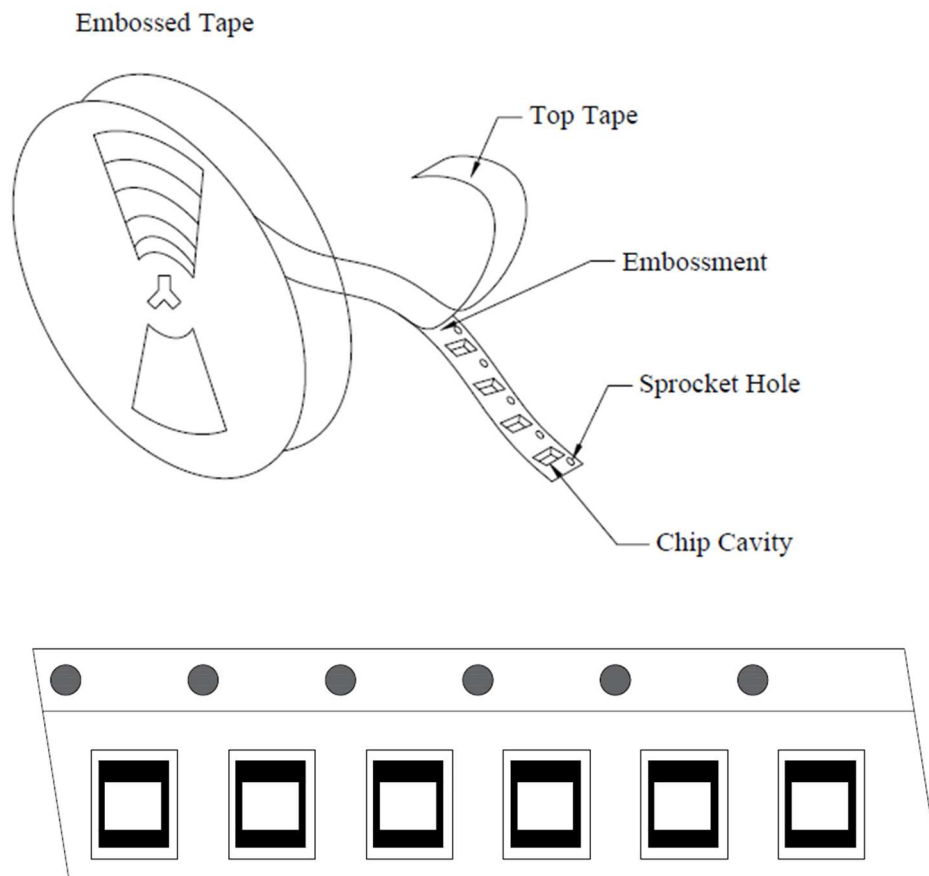
Packaging

Tape Carrier Packaging:

Tape carrier packaging quantity please see the following table:

Type	1005[0402]
Tape	Paper Tape
Quantity	10K

Taping Drawings (Unit: mm)



Multi-layer Chip Diplexer



ADID-R-0004

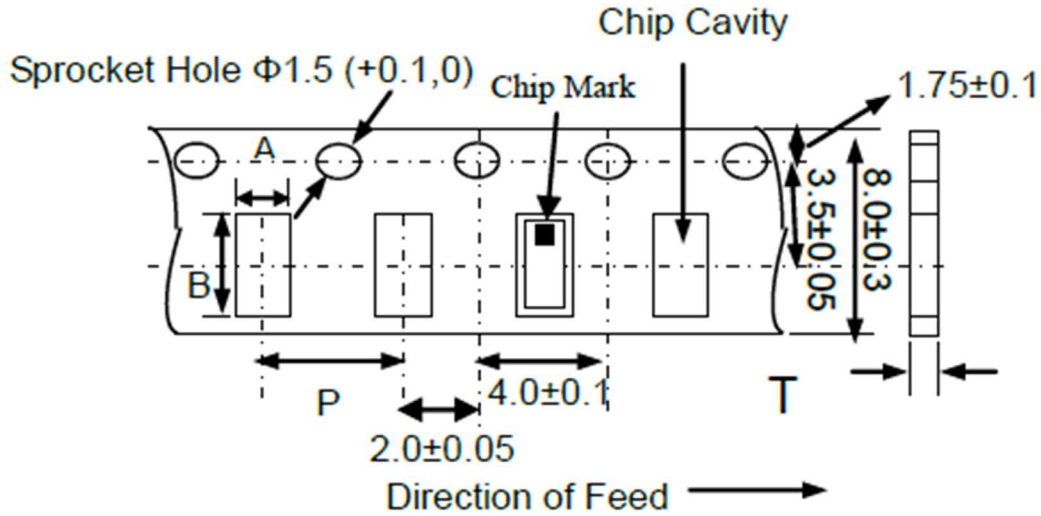
Request Samples

Check Inventory

1.0 x 0.5 x 0.4 mm

RoHS Compliant

Taping Dimensions (Unit: mm)



A	B	P	T max
0.65 ± 0.1	1.15 ± 0.10	2.0 ± 0.05	0.6

Multi-layer Chip Diplexer



ADID-R-0004

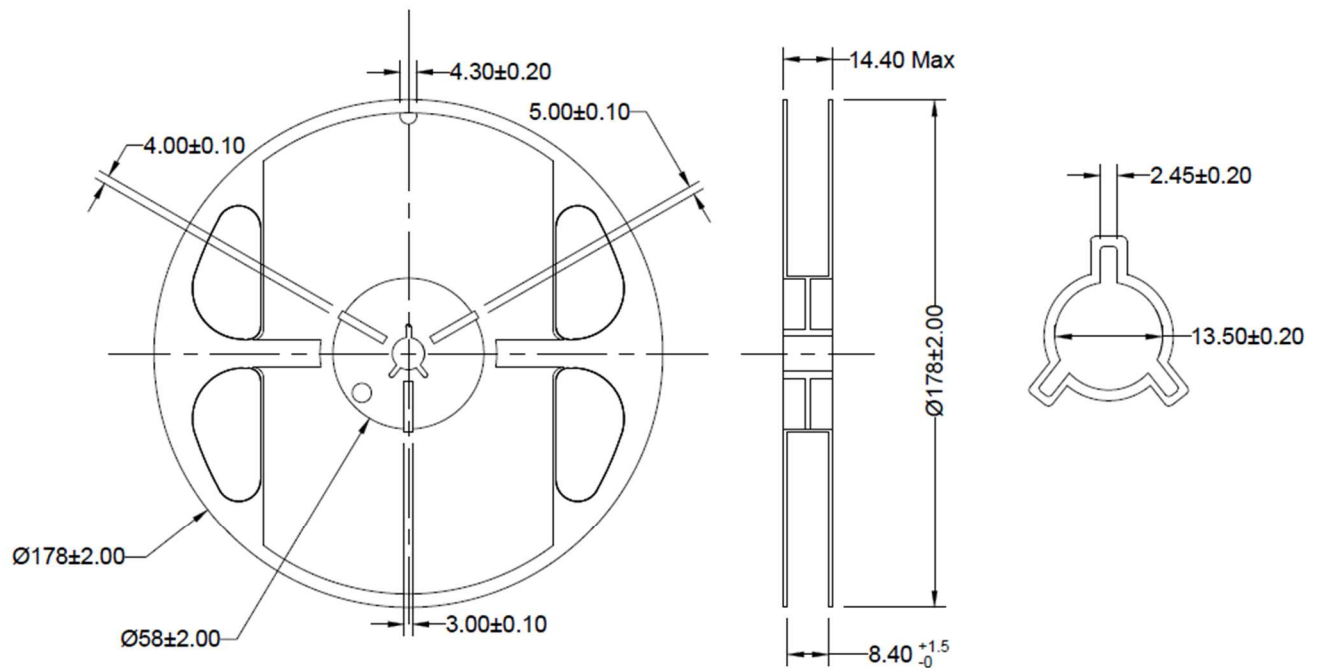
Request Samples

Check Inventory

1.0 x 0.5 x 0.4 mm

RoHS Compliant

Reel Dimensions (Unit: mm)



Unit: mm

ATTENTION: Abracon LLC's products are COTS – Commercial-Off-The-Shelf products; suitable for Commercial, Industrial and, where designated, Automotive Applications. Abracon's products are not specifically designed for Military, Aviation, Aerospace, Life-dependent Medical applications or any application requiring high reliability where component failure could result in loss of life and/or property. For applications requiring high reliability and/or presenting an extreme operating environment, written consent and authorization from Abracon LLC is required. Please contact Abracon LLC for more information.



5101 Hidden Creek Ln Spicewood TX 78669
Phone: 512-371-6159 | Fax: 512-351-8858
For terms and conditions of sales, please visit:
www.abracon.com

REVISED: 02-19-24

ABRACON IS
ISO9001-2015
CERTIFIED